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# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	80	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	180	A
	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	180	
$I_{DM}^{(2)}$	Drain current (pulsed)	720	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	315	W
$E_{AS}^{(3)}$	Single pulse avalanche energy	0.775	J
$T_{stg}$	Storage temperature range	-55 to 175	$^\circ\text{C}$
$T_j$	Operating junction temperature range		

**Notes:**

- (1) Limited by package.
- (2) Pulse width is limited by safe operating area.
- (3) Starting  $T_j = 25\text{ }^\circ\text{C}$ ,  $I_d = 65\text{ A}$ ,  $V_{dd} = 50\text{ V}$ ,  $T_j < T_{j-max}$ .

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.48	$^\circ\text{C/W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	35	

**Notes:**

- (1) When mounted on FR-4 board of 1 inch<sup>2</sup>, 2oz Cu.

## 2 Electrical characteristics

(T<sub>CASE</sub> = 25 °C unless otherwise specified)

**Table 4: On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	80			V
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 80 V			1	μA
		V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 80 V, T <sub>C</sub> = 125 °C <sup>(1)</sup>			100	
I <sub>GSS</sub>	Gate-body leakage current	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = +20 V			100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.5		4.5	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 90 A		1.7	2.1	mΩ

**Notes:**

<sup>(1)</sup> Defined by design, not subject to production test.

**Table 5: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> = 50 V, f = 1 MHz, V <sub>GS</sub> = 0 V	-	13600	-	pF
C <sub>oss</sub>	Output capacitance		-	2050	-	
C <sub>rss</sub>	Reverse transfer capacitance		-	236	-	
Q <sub>g</sub>	Total gate charge	V <sub>DD</sub> = 40 V, I <sub>D</sub> = 180 A, V <sub>GS</sub> = 10 V (see <a href="#">Figure 14: "Test circuit for gate charge behavior"</a> )	-	193	-	nC
Q <sub>gs</sub>	Gate-source charge		-	96	-	
Q <sub>gd</sub>	Gate-drain charge		-	46	-	

**Table 6: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 40 V, I <sub>D</sub> = 90 A R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 10 V (see <a href="#">Figure 18: "Switching time waveform"</a> )	-	56	-	ns
t <sub>r</sub>	Rise time		-	180	-	
t <sub>d(off)</sub>	Turn-off delay time		-	98	-	
t <sub>f</sub>	Fall time		-	42	-	

Table 7: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		180	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		720	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 90 \text{ A}$	-		1.2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 180 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 64 \text{ V}$ , $T_j = 150 \text{ }^\circ\text{C}$	-	78		ns
$Q_{rr}$	Reverse recovery charge		-	182		nC
$I_{RRM}$	Reverse recovery current		-	4.7		A

**Notes:**

(1) Pulse width limited by safe operating area.

(2) Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.

## 2.1 Electrical characteristics (curves)

Figure 2: Safe operating area

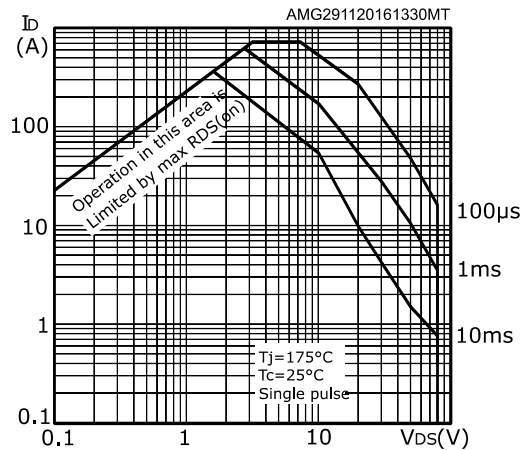


Figure 3: Thermal impedance

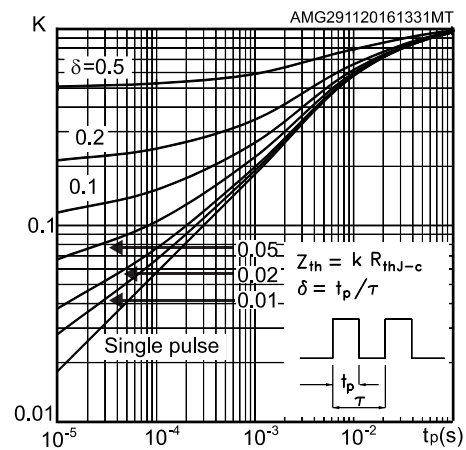


Figure 4: Gate charge vs gate-source voltage

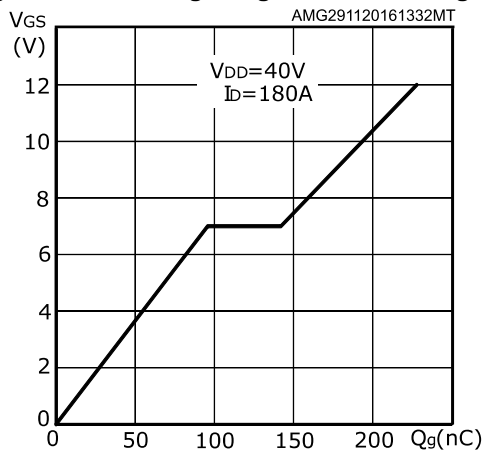


Figure 5: Output characteristics

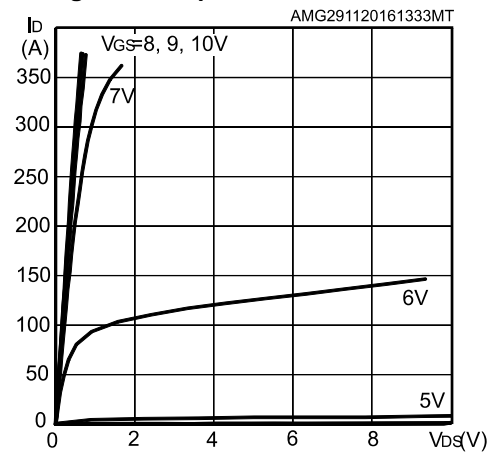


Figure 6: Transfer characteristics

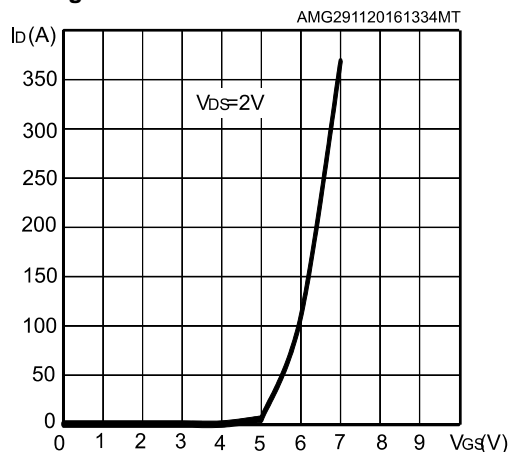
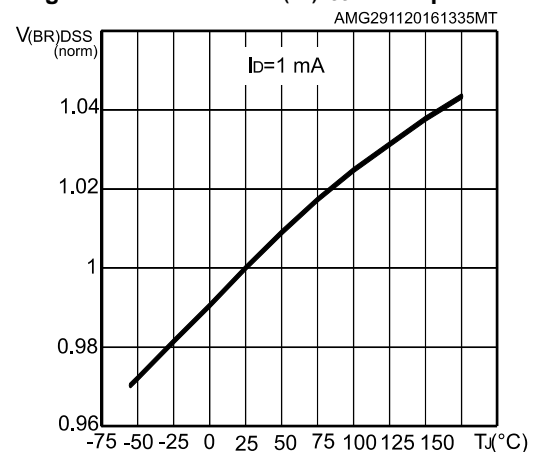
Figure 7: Normalized  $V_{(BR)DSS}$  vs temperature

Figure 8: Static drain-source on-resistance

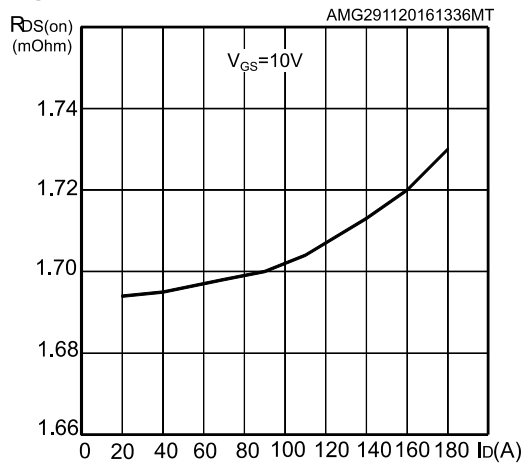


Figure 9: Capacitance variations

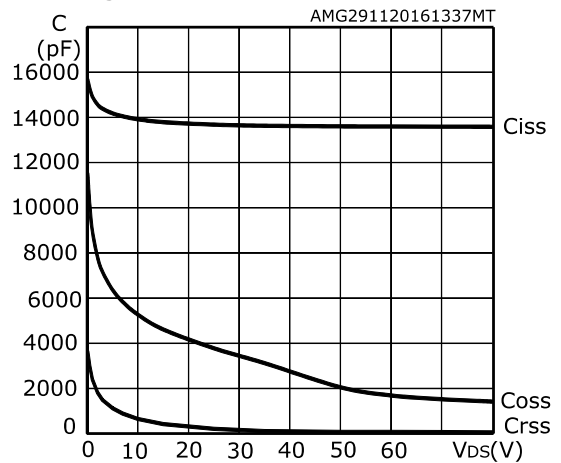


Figure 10: Source-drain diode forward characteristics

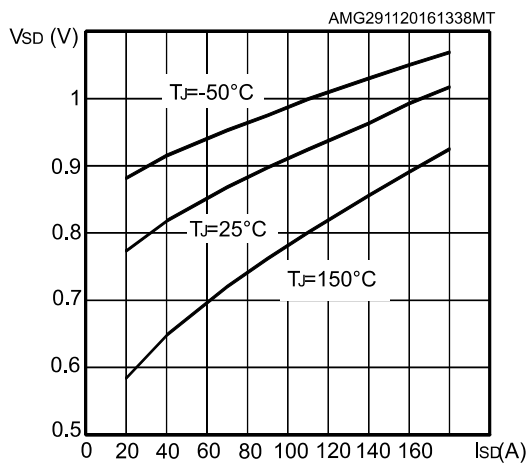


Figure 11: Normalized gate threshold voltage vs temperature

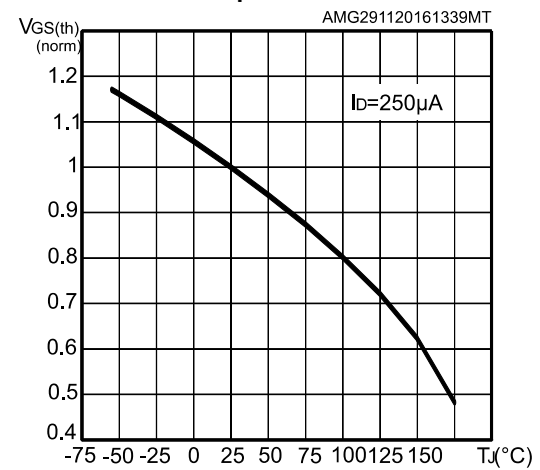
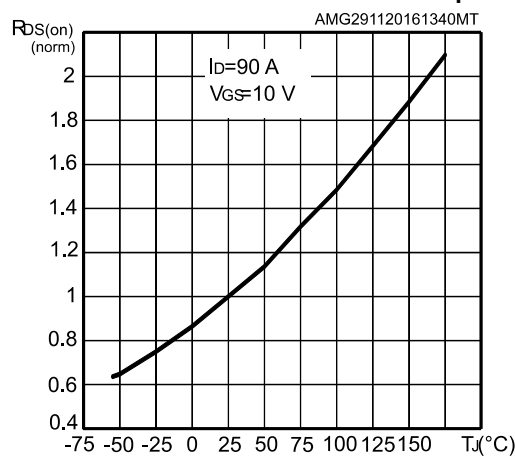
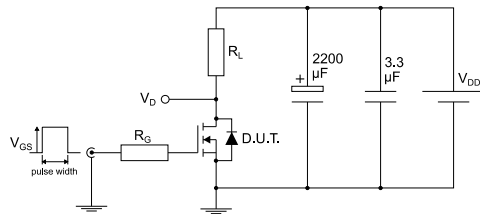


Figure 12: Normalized on-resistance vs temperature



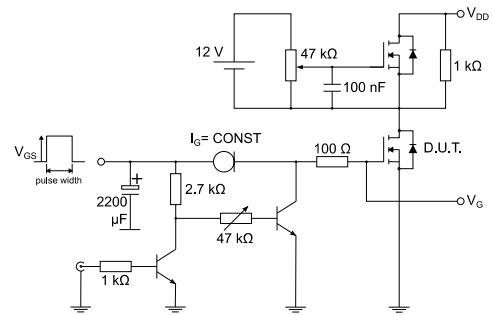
### 3 Test circuits

**Figure 13: Test circuit for resistive load switching times**



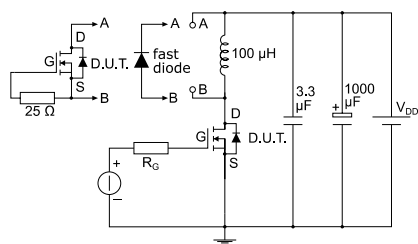
AM01468v1

**Figure 14: Test circuit for gate charge behavior**



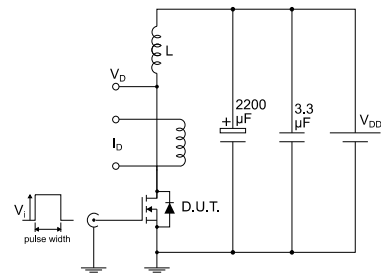
AM01469v1

**Figure 15: Test circuit for inductive load switching and diode recovery times**



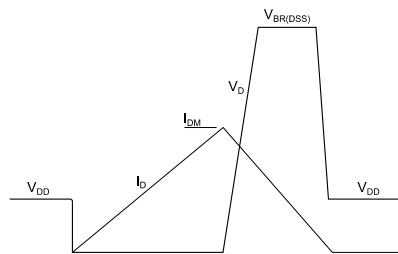
AM01470v1

**Figure 16: Unclamped inductive load test circuit**



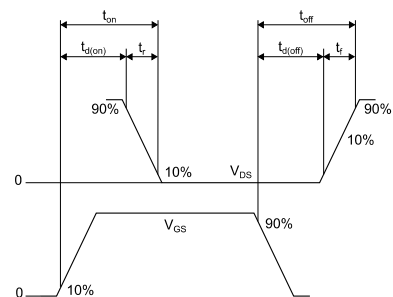
AM01471v1

**Figure 17: Unclamped inductive waveform**



AM01472v1

**Figure 18: Switching time waveform**



AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **[www.st.com](http://www.st.com)**. ECOPACK® is an ST trademark.



## 4.1 H<sup>2</sup>PAK-2 package information

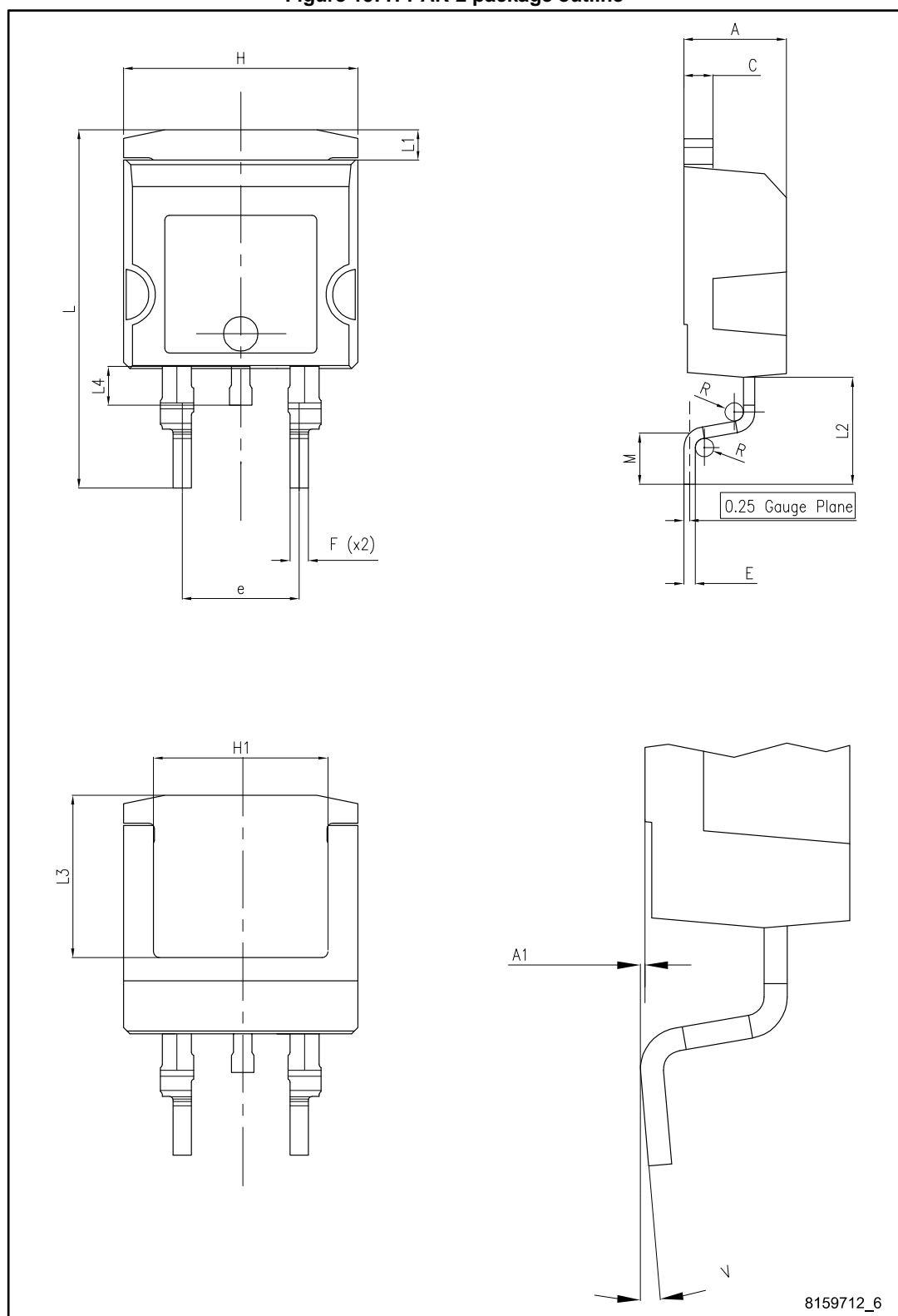
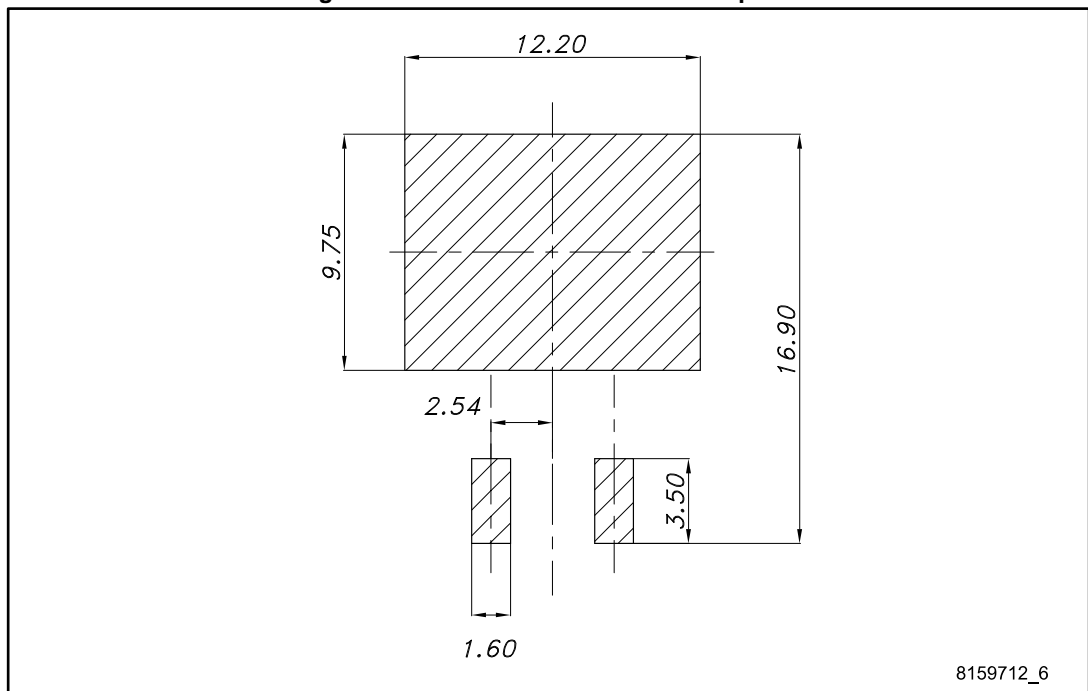
Figure 19: H<sup>2</sup>PAK-2 package outline

Table 8: H<sup>2</sup>PAK-2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.30	-	4.70
A1	0.03		0.20
C	1.17		1.37
e	4.98		5.18
E	0.50		0.90
F	0.78		0.85
H	10.00		10.40
H1	7.40		7.80
L	15.30		15.80
L1	1.27		1.40
L2	4.93		5.23
L3	6.85		7.25
L4	1.5		1.7
M	2.6		2.9
R	0.20		0.60
V	0°		8°

Figure 20: H<sup>2</sup>PAK-2 recommended footprint



## 4.2 H<sup>2</sup>PAK-6 package information

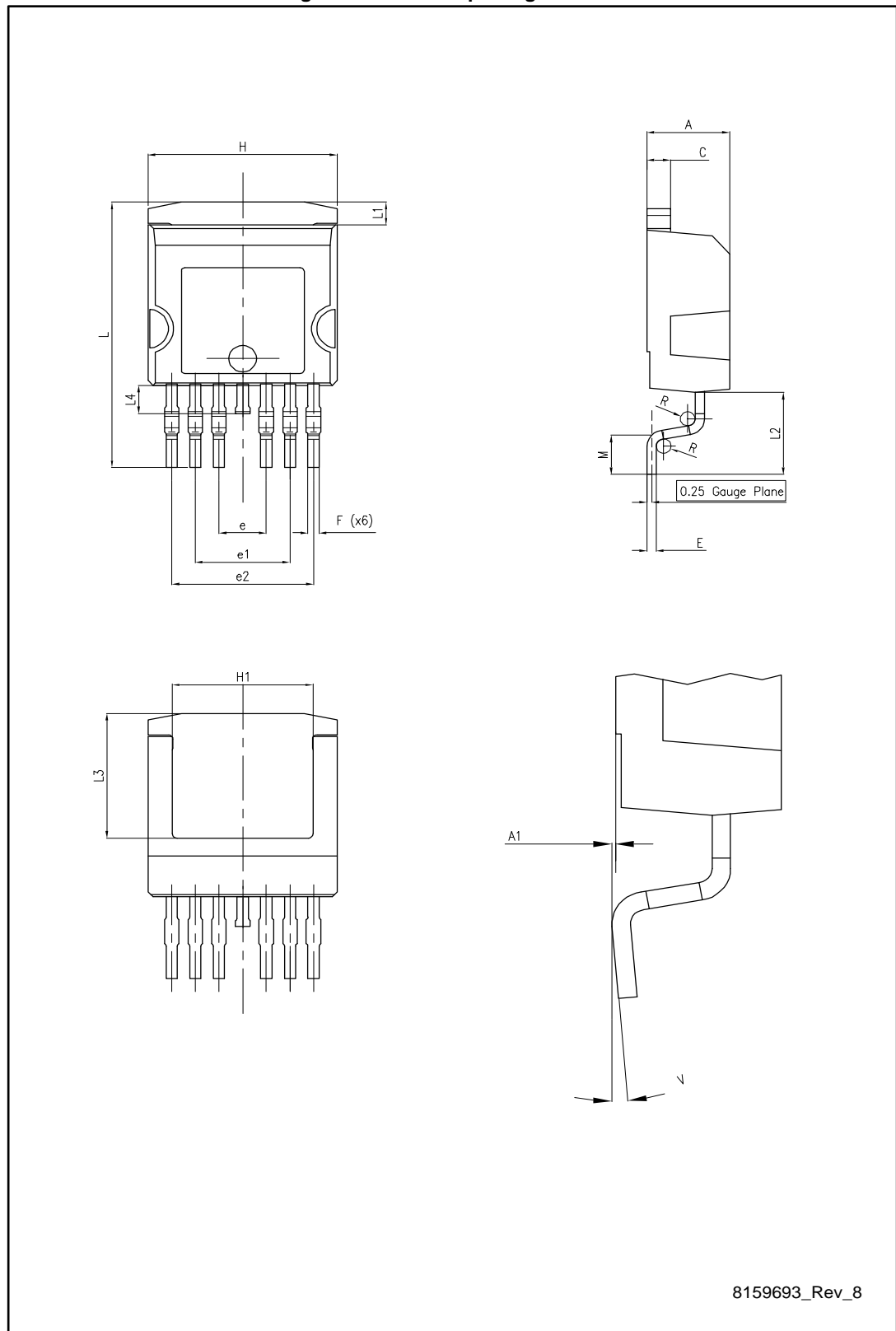
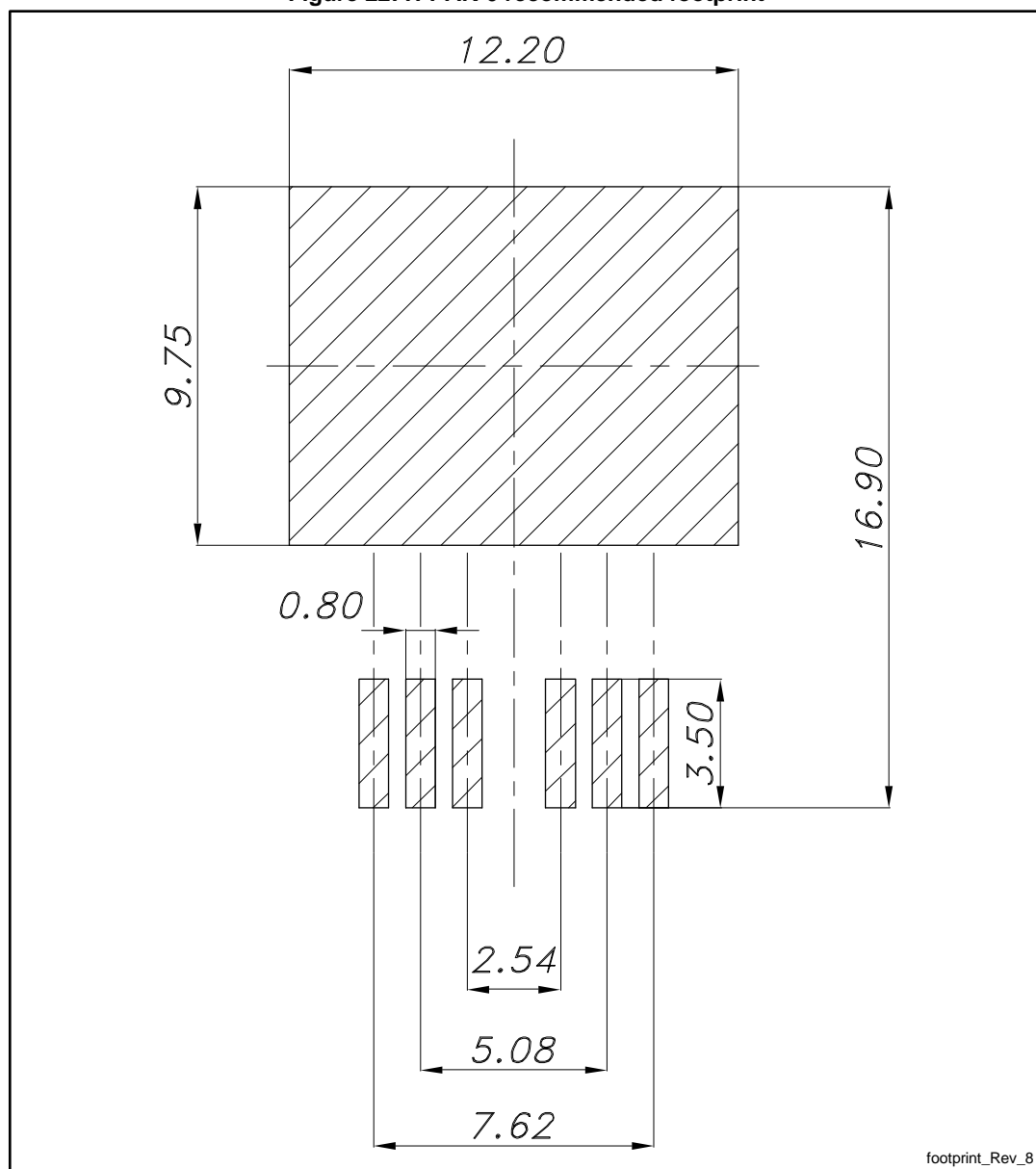
Figure 21: H<sup>2</sup>PAK-6 package outline

Table 9: H<sup>2</sup>PAK-6 package mechanical data

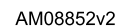
Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.70
A1	0.03		0.20
C	1.17		1.37
e	2.34	2.54	2.74
e1	4.88		5.28
e2	7.42		7.82
E	0.45		0.60
F	0.50		0.70
H	10.00		10.40
H1	7.40		7.80
L	14.75		15.25
L1	1.27		1.40
L2	4.35		4.95
L3	6.85		7.25
L4	1.50		1.75
M	1.90		2.50
R	0.20		0.60
V	0°		8°

Figure 22: H<sup>2</sup>PAK-6 recommended footprint

Dimensions are in mm.

### 4.3 H<sup>2</sup>PAK packing information

### Figure 23: Tape outline



### Figure 24: Reel outline

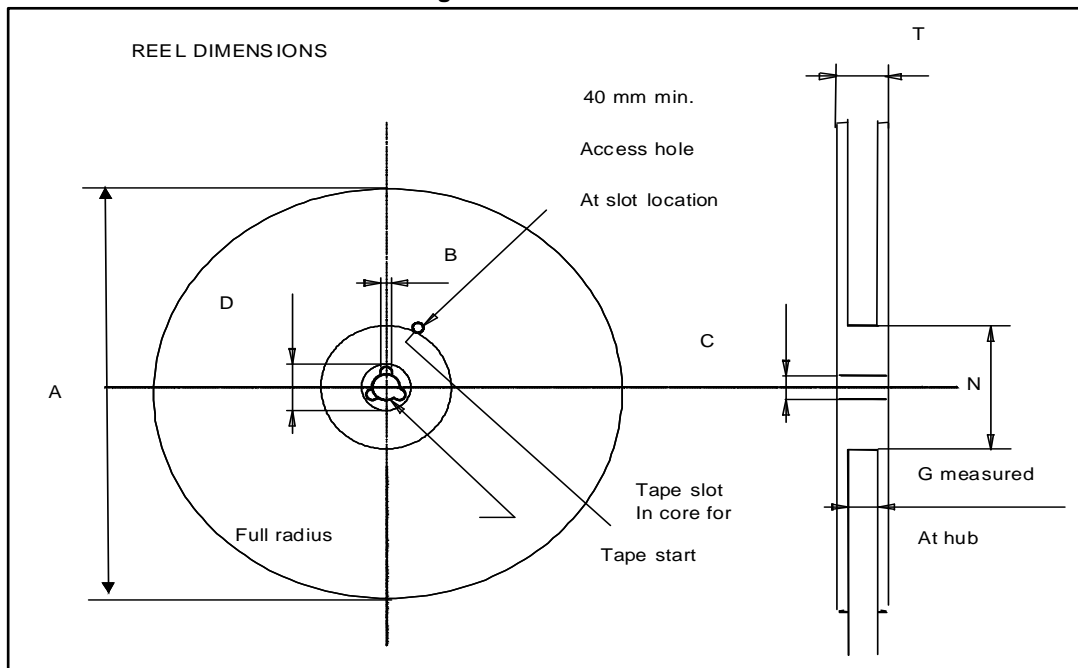


Table 10: Tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 5 Revision history

**Table 11: Document revision history**

Date	Revision	Changes
27-Nov-2014	1	First release.
05-Mar-2015	2	Document status promoted from preliminary to production data. Updated title and feature in cover page.
10-Mar-2016	3	Updated Table 4. Minor text changes.
10-Jan-2017	4	Updated title and features in cover page. Updated <a href="#">Table 2: "Absolute maximum ratings"</a> , <a href="#">Table 4: "On/off states"</a> and <a href="#">Table 6: "Switching times"</a> . Minor text changes.



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